

## ABSTRACT OF THE DISCLOSURE

An assembly includes a first semiconductor die with bond pads arranged in an array on an active surface thereof and at least one second semiconductor die with bond pads on an active surface thereof flip-chip connected to bond pads of the first semiconductor device. The at least one second semiconductor die is oriented with the active surface thereof facing the active surface of the first semiconductor die. Corresponding bond pads of the first and at least one second semiconductor dice are connected by placing or forming conductive structures therebetween. A package includes the assembly and a carrier. The first semiconductor die of the assembly is oriented over the carrier with the active surface of the first semiconductor die facing the carrier. Bond pads of the first semiconductor die located laterally beyond an outer periphery of each second semiconductor die are electrically connected to corresponding contacts by way of conductive structures.

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